	Type	Hits	Search Text	DBs
1	BRS	410	"chip on chip" or "stacked chip"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB
2	BRS	410	257/777 and "chip on chip" or "stacked chip"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB
3	BRS	1000	257/777 not ("chip on chip" or "stacked chip")	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB
4	BRS	2001	361/760 not ("chip on chip" or "stacked chip")	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB
5	BRS	228	361/760 not ("chip on chip" or "stacked chip") and solder adj ball and wire	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB
6	BRS	306	361/760 not ("chip on chip" or "stacked chip") and solder adj (ball or bump) and wire and pad	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB
7	BRS	167	438/108 not ("chip on chip" or "stacked chip") and solder adj (ball or bump) and wire and pad	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB
8	BRS	69	438/109 not ("chip on chip" or "stacked chip") and solder adj (ball or bump) and wire and pad	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB
9	BRS	3	5715147.pn. or 5903049.pn. or 6031279.pn.	USPAT
10	BRS	4	5715147.pn. or 5903049.pn. or 6031279.pn. or 6100594.pn.	USPAT
11	BRS	2	2000124395.pn. or 200194045.pn. or 10256470.pn.	JPO
12	BRS	0	200194045.pn.	JPO
13	BRS	1	6100594.pn.	USPAT; JPO

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	Type	Hits	Search Text	DBs
1	BRS	3	257/$.ccls. and (size or small) near ((adhesive or glue) adj (layer or film))	USPAT; JPO
2	BRS	152	257/777 and ((adhesive or glue) adj (layer or film))	USPAT; JPO
3	BRS	1083	257/777	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB
4	BRS	2	2000124395.pn. or P200194045.pn. or 10256470.pn.	JPO
5	BRS	6	2000124395.pn. or 200194045.pn. or 10256470.pn. or 6181002.pn. or 5291061.pn. or 6133626.pn. or 6100594.pn.	USPAT; JPO
6	BRS	1	5012323.pn.	USPAT; JPO